

DWG. NO. SD-53309-**-27

E

D

C

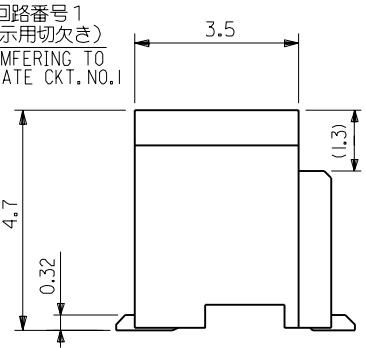
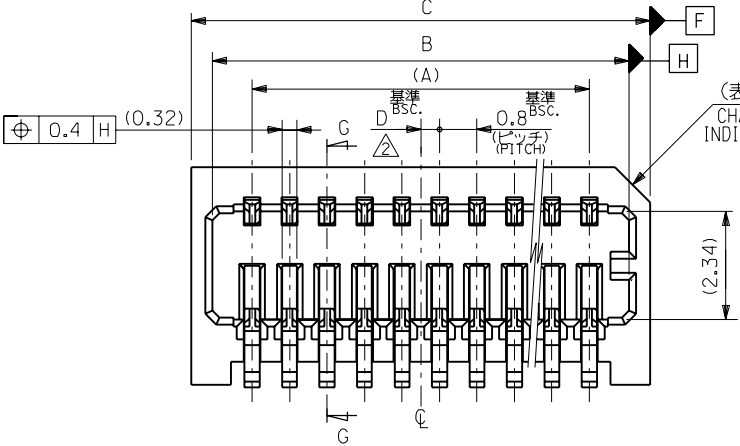
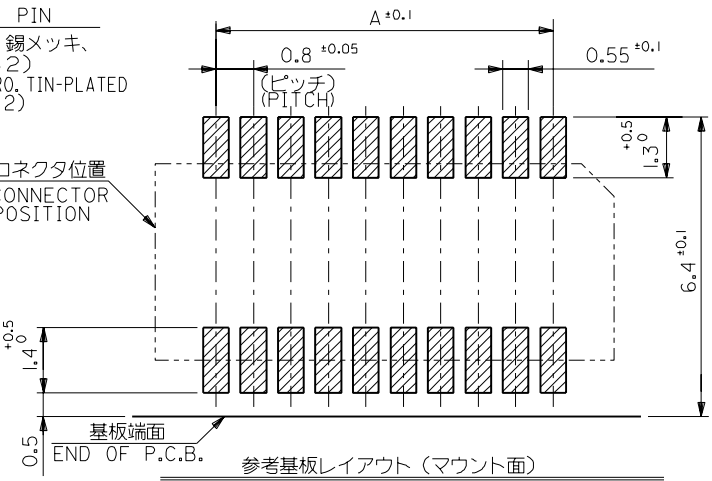
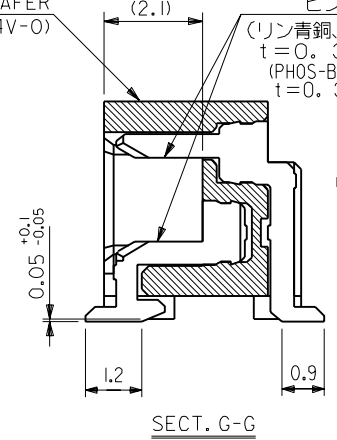
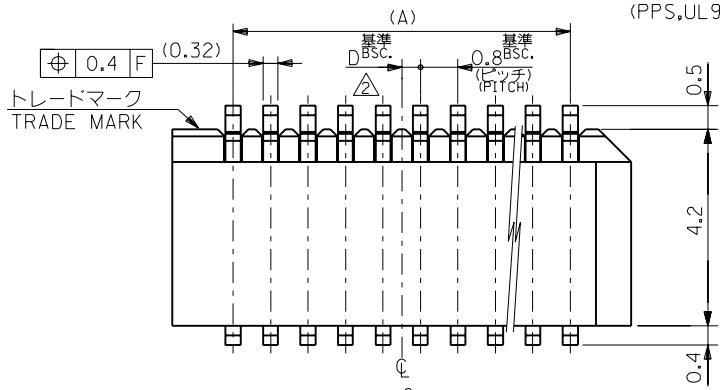
B

A

MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

ウェハ WAFER (PPS,UL94V-O)

ピン PIN (リン青銅、錫メッキ、 $t=0.32$) (PHOS-BRO. TIN-PLATED $t=0.32$)



参考基板レイアウト (マウント面)
P.C.B. PATTERN LAYOUT (REF.) (MOUNT AREA)

0.4	17.8	16.9	15.2	53309-4027	40
0.8	17.0	16.1	14.4	-3827	38
0.4	16.2	15.3	13.6	-3627	36
0.8	15.4	14.5	12.8	-3427	34
0.4	14.6	13.7	12.0	-3227	32
0.8	13.8	12.9	11.2	-3027	30
0.4	13.0	12.1	10.4	-2827	28
0.8	12.2	11.3	9.6	-2627	26
0.4	11.4	10.5	8.8	-2427	24
0.8	10.6	9.7	8.0	-2227	22
0.4	9.8	8.9	7.2	-2027	20
0.8	9.0	8.1	6.4	-1827	18
0.4	8.2	7.3	5.6	-1627	16
0.8	7.4	6.5	4.8	-1427	14
0.4	6.6	5.7	4.0	-1227	12
0.8	5.8	4.9	3.2	53309-1027	10
D	C	B	A	ENG. NO.	極数 CKT.

注記 NOTES

1. 炭合相手: 52465,52588 シリーズ
MATE WITH: 52465,52588 SERIES
- △ ウェハの C から隣接するピンの C 迄の位置を示す。
SHOW POSITION FROM C OF WAFER TO C OF ADJACENT PINS.

角度 ANGLE	公差 TOLERANCES	記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
30 以上 OVER	+0.3	B	変更 REVISD (JC60094)	M.H.	'95/8/9
10 以上 30 未満 UNDER	+0.25	A	変更 REVISD (J30447)	T.C.	'93/5/1
10 未満 UNDER	+0.2	O	新規作成 PROPOSED (J11001)	M.H.	'91/11/15

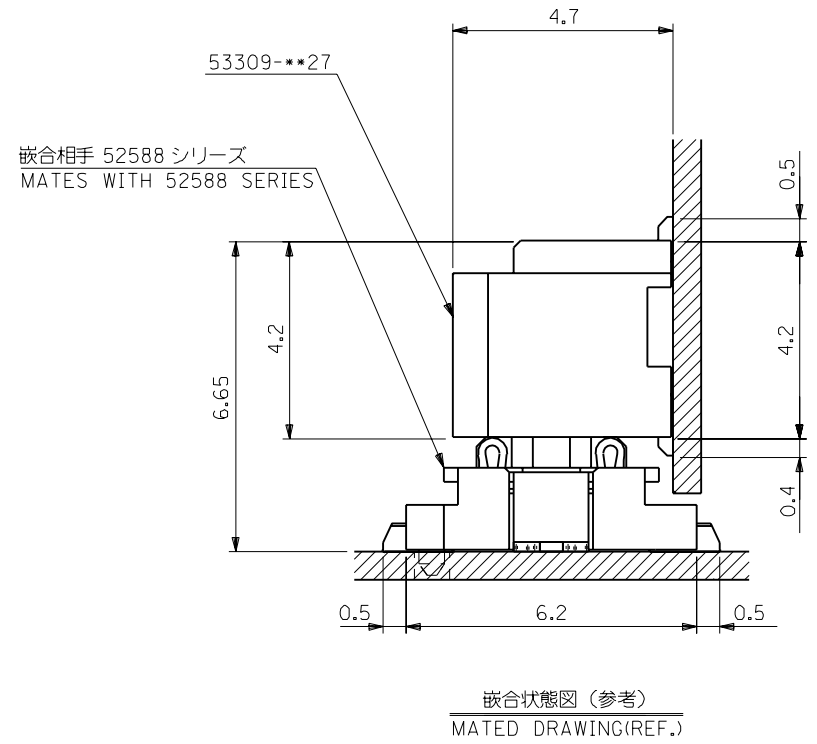
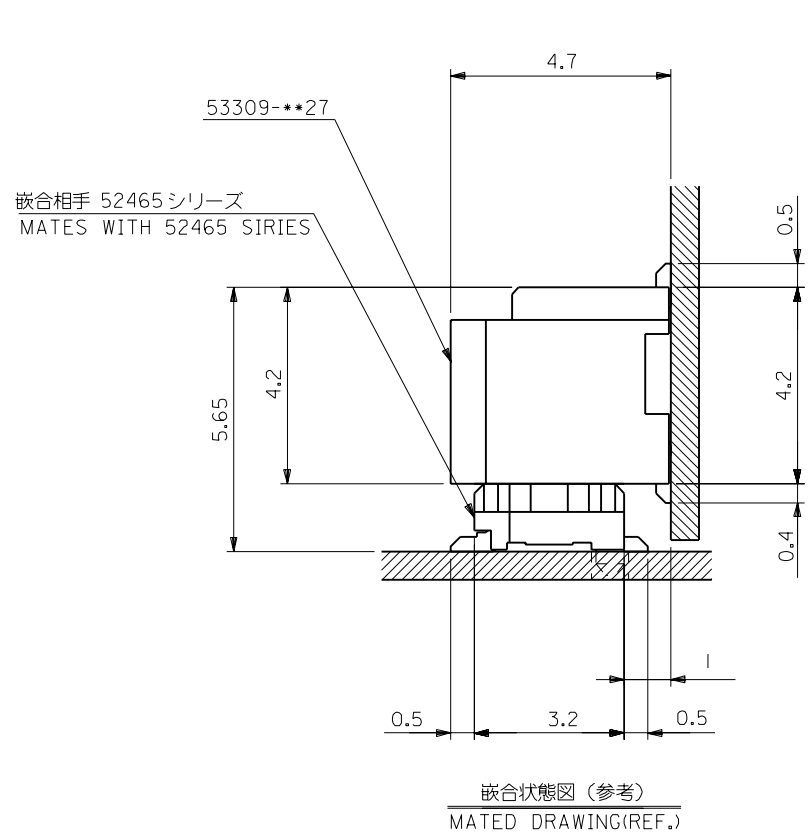
材料 MATERIAL	☑ 中参照 SEE DRAWING
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '91/11/14	CHK'D BY '95/8/9
K.ASAKAWA	Y.M.HIRAMOTO
APP'D BY '95/8/9	尺度 SCALE
M.FUKUSHIMA	—

MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
0.8 BOARD TO BOARD CONN.
WAFER ASS'Y R/A SMT
(WITHOUT BOSS)

DWG. NO. (SHEET 1 OF 2) REV
SD-53309-**-27 B



角度 ANGLE	公差	記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
30°以上 OVER	+0.3	B	変更 (JC60094)	M.N.H.	'95/8/9
10°以上 30°未満 OVER UNDER	+0.25	A	変更 (J30447)	T.S.	'93/5/11
10°未満 UNDER	+0.2	O	新規作成 (J11001)	M.F.	'91/11/15
一般公差 GENERAL TOLERANCES					

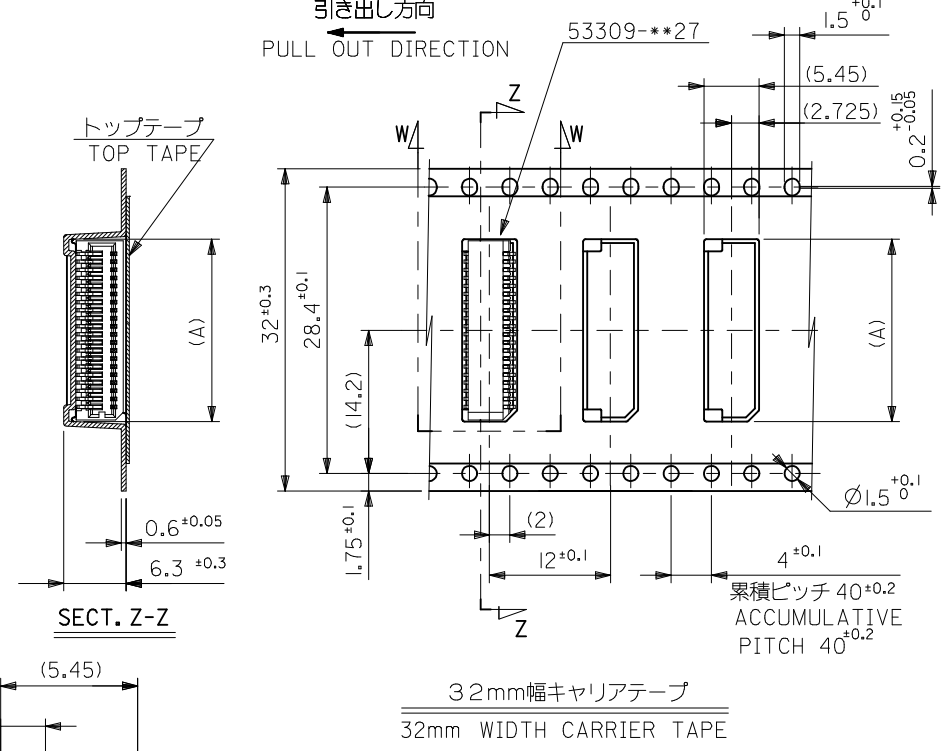
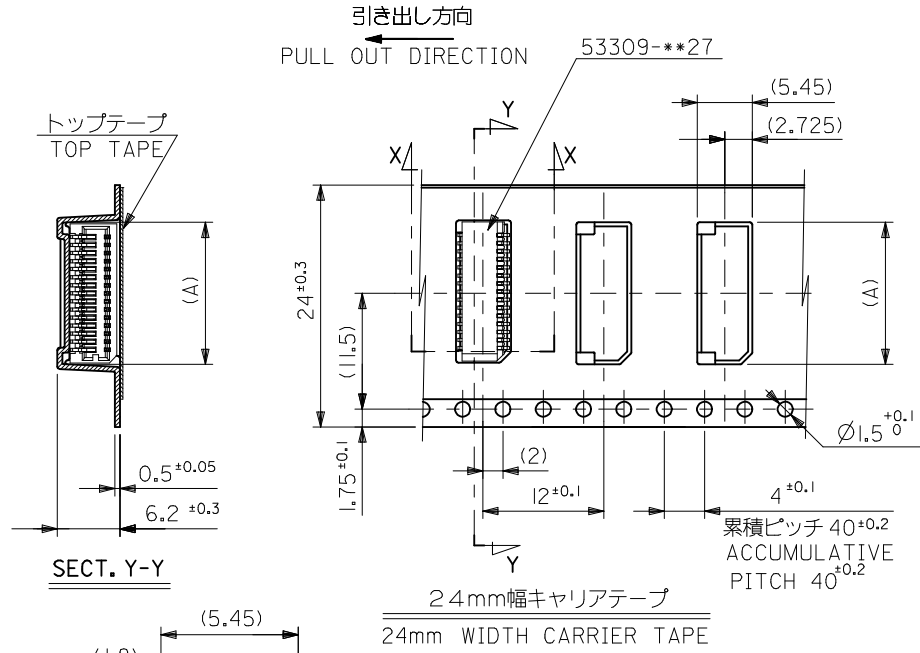
材料 MATERIAL	SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '91/11/14	CHK'D BY '95/8/9
K.ASAKAWA	Y.M.HIRAMOTO
APP'D BY '95/8/9	尺度 SCALE
M.FUKUSHIMA	—

molex MOLEX-JAPAN CO.,LTD.
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REVISE ONLY ON CAD SYSTEM

TITLE 名称
0.8 BOARD TO BOARD CONN.
WAFER ASS'Y R/A SMT
(WITHOUT BOSS)

DWG. NO. (SHEET 2 OF 2) REV
SD-53309-***27 B



32	33.5	18.1	53309-4091	40
24	25.5	14.1	53309-3091	30
		10.1	53309-2091	20
キャリアテープ幅 CARRIER TAPE WIDTH	B	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2009-1528 DRWN: MAKURAA 2008/12/17 CHKD: T. HARUYAMA 2008/12/17 APPR: NUKITA 2009/01/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 53309-***91
	10 UNDER	± ---	DRAWN BY K. ASAKAWA	DATE '91/11/22	TITLE 0.8 BTB CONN WAFER ASSY RA SMT WITHOUT BOSS EMBSTP PAG		
	10 OVER 30 UNDER	± ---	CHECKED BY T. ITO	DATE '00/12/6	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY M. FUKUSHIMA	DATE '00/12/6	DOCUMENT NO. SD-53309-016	SHEET NO. 2 OF 2	
	ANGULAR ± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			